

PIN RECEPTACLES WITH ORGANIC FIBRE PLUG[®] SOLDER BARRIER (SEE SPECIFIC CONTACT RANGE ON PAGES 250, 251 & 253)

0

0

- These through-hole (tubular) receptacles are designed for hand, wave or reflow * soldering. The ORGANIC FIBRE PLUG[®] barrier prevents solder paste or flux from contaminating the spring contact.
- After soldering, the OFP[®] barrier is pushed out of the receptacle when the device is plugged in.
- All parts are available as discrete receptacles or supplied on carrier tape per EIA-481 to feed industry standard pick and place machines.

* Intrusive reflow (also called "pin-in-paste") is a technique of using conventional through-hole components in a reflow soldering process. The receptacles are placed into plated through-holes in the circuit board (solder paste has previously been screen printed on pads adjacent to the holes) and the

board is reflowed in the same pass as other SMT components. Solder will fill the plated through-holes and achieve solder joints as reliable as wave soldering. The OFP[®] barrier prevents solder paste from being picked-up inside the contact during pick 'n place assembly. "Overprinting" paste on the solder mask can be used to adjust the volume of paste required to fill each hole.



